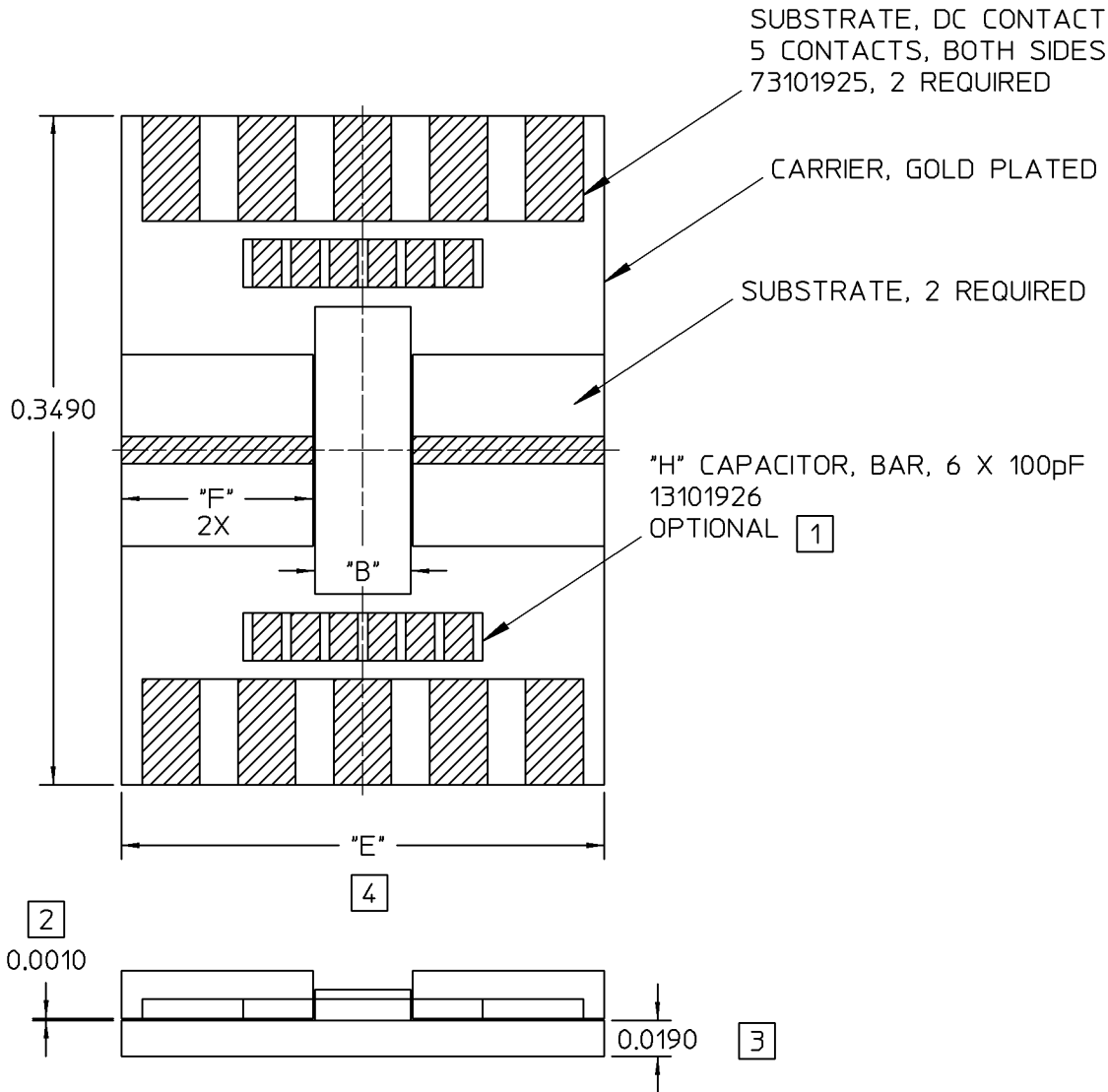
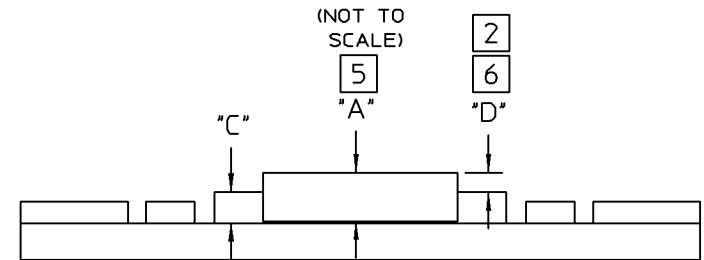


REV	ECN NO.	INIT	DATE



A = \_\_\_\_\_ = SUBSTRATE THICKNESS  
 B = \_\_\_\_\_ = PEDESTAL WIDTH  
 C = \_\_\_\_\_ = PEDESTAL HEIGHT = A + 0.001 - D  
 D = \_\_\_\_\_ = DUT THICKNESS + DUT ATTACHMENT  
 E = \_\_\_\_\_ = 2(F) + 0.006 + B [4]  
 F = 0.1000 = SUBSTRATE LENGTH  
 G: SELECT SUBSTRATE ATTACHMENT  
 SILVER EPOXY OR  AuGe SOLDER  
 H: CAPACITOR OPTION  YES  NO [1]



**MANUFACTURING NOTES:**

- [1] CAPACITOR BARS: OPTIONAL
- [2] ALLOW 0.0010 THICKNESS FOR SUBSTRATE ATTACHMENT
- [3] 0.0190 IS CARRIER THICKNESS
- [4] 0.003 GAP REQUIRED BETWEEN PEDESTAL AND SUBSTRATES.
- [5] \*A\* DIMENSION IS SUBSTRATE THICKNESS (10, 15 OR 25 MILS)
- [6] \*D\* DIMENSION IS TOP OF PEDESTAL TO TOP OF SUBSTRATE

INTERCONTINENTAL MICROWAVE			
MMIC CARRIER ASSY			
DATA INPUT FORM			
SIZE	PART NO.	REV	VER.
A	B0137207		